

Attorney Docket No.: CPAC 1017-5
Application No. 10/632,552

PATENT

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (previously presented) A multi-package module comprising first and second packages, each said package including a die attached to a passive substrate, each said substrate having a die attach side and a land side, wherin the second package is stacked over the first package such that a portion of the land side of the second package opposite the second package die is affixed to a surface of the first package, wherein the first and second substrates are interconnected by wire bonding, and wherein the first package comprises a flip-chip ball grid array package having a flip-chip in a dic-up configuration.
2. (original) The multi-package module of claim 1 wherein the second package is a wire bonded land grid array package.
3. (previously presented) The multi-package module of claim 2 whrcin the second package comprises wire bonds connecting the second package die with the second package substrate and wherein the die and wire bonds in the second package are fully encapsulated with a molding material.
4. (original) The multi-package module of claim 2 wherein the second package is peripherally encapsulated to an extent sufficient to cover the wire bonds between the die and the substrate.
5. (original) The multi-package module of claim 2 whrcin the second package substrate is a single-metal layer substrate.
6. (original) The multi-package module of claim 1 wherein the flip chip package is provided with an electrical shield.

Attorney Docket No.: CPAC 1017-5
Application No. 10/632,552

PATENT

7. (original) The multi-package module of claim 6 wherein the electrical shield is configured to serve as a heat spreader.

8. (original) The multi-package module of claim 1 wherein the flip chip package includes an RF die.

9. (original) The multi-package module of claim 6 wherein the flip chip package includes an RF die, and the shield serves to limit electromagnetic interference between the RF die and other die in the multi-package module.

10. (original) The multi-package module of claim 1 wherein the first package is provided with an electrical shield.

11. (original) The multi-package module of claim 1 wherein the second package is a stacked die package.

12. (original) The multi-package module of claim 11 wherein adjacent stacked die in the stacked die package are separated by spacers.

13. (original) The multi-package module of claim 1 wherein the second package is stacked over the first package, and wherein the flip-chip die on the first package is provided with an electrical shield.

14. (original) The multi-package module of claim 1 wherein the first package substrate includes an embedded ground plane.

15. (original) The multi-package module of claim 14, the ground plane being configured to serve for heat dissipation.

16. (original) The multi-package module of claim 14, the ground plane being configured to serve as an electrical shield.

Attorney Docket No.: CPAC 1017-5
Application No. 10/632,552

PATENT

17. (original) The multi-package module of claim 1 wherein at least one of the first and the second package is a stacked-die package.

18. (canceled).

19. (previously presented) The multi-package module of claim 1, further comprising a heat spreader.

20 - 34. (canceled).

35. (original) A mobile communications device comprising a multi-package module according to claim 1.

36. (original) A computer comprising a multi-package module according to claim 1.

///